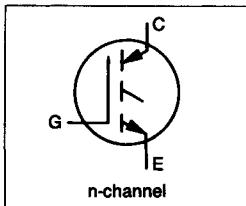


INSULATED GATE BIPOLAR TRANSISTOR

UltraFast™ IGBT



Description

Insulated Gate Bipolar Transistors (IGBTs) from International Rectifier have higher current densities than comparable bipolar transistors, while at the same time having simpler gate-drive requirements of the familiar power MOSFET. They provide substantial benefits to a host of higher-voltage, higher-current applications.

The performance of various IGBTs varies greatly with frequency. Note that IR now provides the designer with a speed benchmark ($f_{I_{Q/2}}$, or the "half-current frequency"), as well as an indication of the current handling capability of the device. Refer to Figure 14.

Product Summary

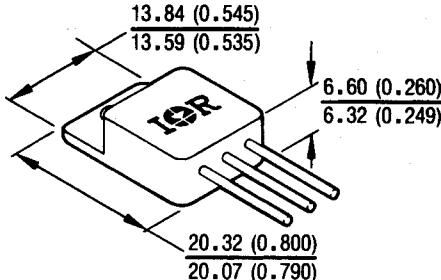
Part Number	$V_{(BR)CES}$	$V_{CE(on)}$	I_C	E_{ts}
IRGMC40U	600V	3.0V	31A	2.0 mJ

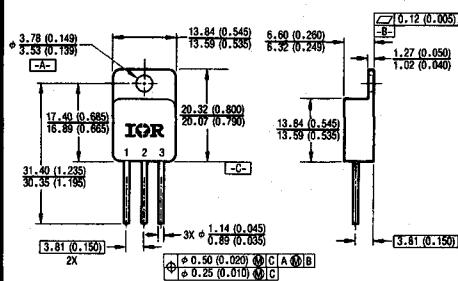
Features:

- Electronically Isolated and Hermetically Sealed
- Simple Drive Requirements
- Latch-proof
- Ultra-fast operation > 10 kHz
- Switching-Loss Rating includes all "tail" losses
- Ceramic Eyelets

G

CASE STYLE AND DIMENSIONS


CAUTION

 BERYLLIA WARNING PER MIL-S-19500
 SEE PAGE G-89


NOTES:

- 1 DIMENSIONING & TOLERANCING PER ANSI Y14.5M - 1982.
- 2 ALL DIMENSIONS ARE SHOWN IN MILLIMETERS (INCHES).

LEGEND

- 1 COLLECTOR
- 2 Emitter
- 3 Gate

*For leadform configuration see page G-89, fig. 15

 Conforms to JEDEC Outline TO-254AA*
 Dimensions in Millimeters and (Inches)

Absolute Maximum Ratings

	Parameter	Max.	Units
$I_C @ T_C = 25^\circ C$	Continuous Collector Current	31	
$I_C @ T_C = 100^\circ C$	Continuous Collector Current	15	A
I_{CM}	Pulsed Collector Current ①	124	
V_{CE}	Collector-to-Emitter Breakdown Voltage	600	V
V_{GE}	Gate-to-Emitter Voltage	± 20	
I_{LM}	Clamped Inductive Load Current ②	124	A
$P_D @ T_C = 25^\circ C$	Maximum Power Dissipation	125	W
$P_D @ T_C = 100^\circ C$	Maximum Power Dissipation	50	
T_J T_{STG}	Operating Junction and Storage Temperature Range	-55 to +150	$^\circ C$
	Lead Temperature, for 10 sec.	300 (0.063 in. (1.6mm) from case)	
	Weight	9.3 (typical)	g

Thermal Resistance

	Parameter	Min.	Typ.	Max.	Units
$R_{\theta JC}$	Junction-to-Case	—	—	1.0	K/W ③
$R_{\theta CS}$	Case-to-Sink, flat, greased surface	—	0.21	—	
$R_{\theta JA}$	Junction-to-Ambient, typical socket mount	—	—	48	

Electrical Characteristic @ $T_J = 25^\circ C$ (unless otherwise specified)

	Parameter	Min.	Typ.	Max.	Units	Test Conditions
$V_{(BR)CES}$	Collector-to-Emitter Breakdown Voltage	600	—	—	V	$V_{GE} = 0V, I_C = 1.0 \text{ mA}$
$V_{(BR)ECS}$	Emitter-to-Collector Breakdown Volt. ③	15	—	—		$V_{GE} = 0V, I_C = 1.0A$
$\Delta V_{(BR)CES}/\Delta T_J$	Temp. Coeff. of Breakdown Voltage	—	0.63	—	$V/^\circ C$	$V_{GE} = 0V, I_C = 1.0 \text{ mA}$
$V_{CE(on)}$	Collector-to-Emitter Saturation Voltage	—	—	3.0	V	$V_{GE} = 15V, I_C = 15A$ See Fig. 4
		—	—	2.7		$V_{GE} = 15V, I_C = 31A$
		—	—	2.3		$V_{CE} = 15V, I_C = 15A, T_J = 125^\circ C$
		3.0	—	5.5		$V_{CE} = V_{GE}, I_C = 250 \mu A$
$\Delta V_{GE(th)}/\Delta T_J$	Temp. Coeff. of Threshold Voltage	—	-13	—	$mV/^\circ C$	$V_{CE} = V_{GE}, I_C = 250 \mu A$
g_{fe}	Forward Transconductance ④	11	—	—	S	$V_{CE} \geq 15V, I_C = 15A$
I_{CES}	Zero Gate Voltage Collector Current	—	—	50	μA	$V_{GE} = 0V, V_{CE} = 480V, T_J = 25^\circ C$
		—	—	2500		$V_{GE} = 0V, V_{CE} = 480V, T_J = 125^\circ C$
I_{GES}	Gate-to-Emitter Leakage Current	—	—	± 500	nA	$V_{GE} = \pm 20V$

Notes:

- ① Repetitive rating; $V_{GE} = 20V$, pulse width limited by max. junction temperature (See figure 12b).
- ② $V_{CC} = 80\%$ (BV_{CES}), $V_{GE} = 20V$, $L \geq 10 \mu H$, $R_G = 10\Omega$, (See figure 12a)
- ③ Pulse width $\leq 80 \mu s$; duty factor $\leq 0.1\%$.
- ④ Pulse width $\leq 5 \mu s$, single shot
- ⑤ K/W equivalent to $^\circ C/W$

Switching Characteristics @ $T_J = 25^\circ\text{C}$ (unless otherwise specified)

	Parameter	Min.	Typ.	Max.	Units	Test Conditions
Q_G	Total Gate Charge (turn-on)	—	50	100	nC	$I_C = 15\text{A}$, $V_{CC} = 300\text{V}$ See Figure 6. $V_{GE} = 15\text{V}$
Q_{GE}	Gate - Emitter Charge (turn-on)	—	9	18		
Q_{GC}	Gate - Collector Charge (turn-on)	—	20	40		
$t_{d(on)}$	Turn-On Delay Time	—	—	50	ns	See test circuit, figure 13. $I_C = 15\text{A}$, $V_{CC} = 480\text{V}$ $T_J = 25^\circ\text{C}$ $V_{GE} = 15\text{V}$, $R_G = 9.1\Omega$ Energy losses include "tail".
t_r	Rise Time	—	—	42		
$t_{d(off)}$	Turn-Off Delay Time	—	—	190		
t_f	Fall Time	—	—	120		
E_{on}	Turn-On Switching Loss	—	0.18	—	mJ	Also see figures 9, 10, & 11.
E_{off}	Turn-Off Switching Loss	—	1.3	—		
E_{ts}	Total Switching Loss	—	1.5	2.0		
$t_{d(on)}$	Turn-On Delay Time	—	25	—	ns	$I_C = 15\text{A}$, $V_{CC} = 480\text{V}$ $T_J = 125^\circ\text{C}$ $V_{GE} = 15\text{V}$ $R_G = 9.1\Omega$
t_r	Rise Time	—	23	—		
$t_{d(off)}$	Turn-Off Delay Time	—	174	—		
t_f	Fall Time	—	140	—		
E_{ts}	Total Switching Loss	—	2.4	—	mJ	
L_E	Internal Emitter Inductance	—	8.7	—	nH	Measured 5mm from package.
C_{iss}	Input Capacitance	—	1500	—	pF	$V_{GE} = 0\text{V}$ $V_{CC} = 30\text{V}$ $f = 1.0 \text{ MHz}$
C_{oss}	Output Capacitance	—	190	—		
C_{res}	Reverse Transfer Capacitance	—	17	—		
C_{cc}	Collector-to-Case Capacitance	—	12	—		

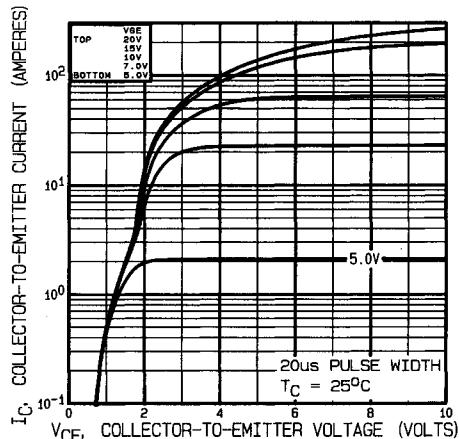


Fig. 1 — Typical Output Characteristics,
 $T_C = 25^\circ\text{C}$

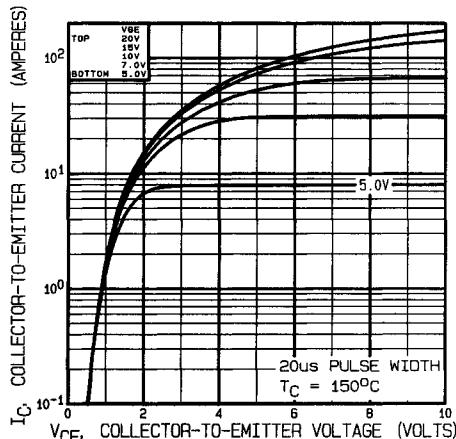


Fig. 2 — Typical Output Characteristics,
 $T_C = 150^\circ\text{C}$

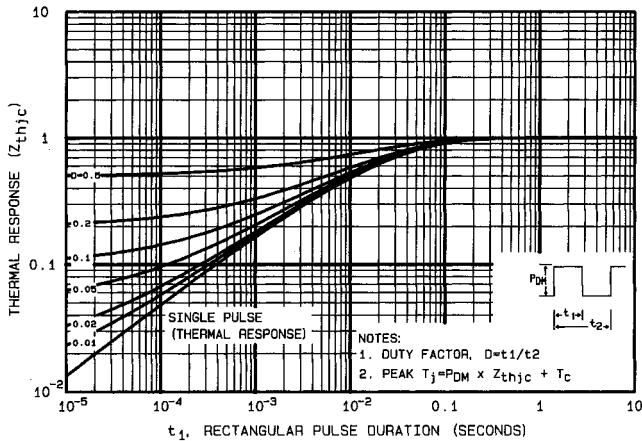


Fig. 7 — Maximum Effective Transient Thermal Impedance, Junction-to-Case

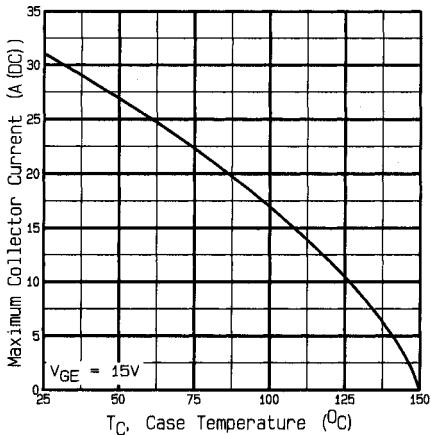


Fig. 8 — Maximum Collector Current vs. Case Temperature

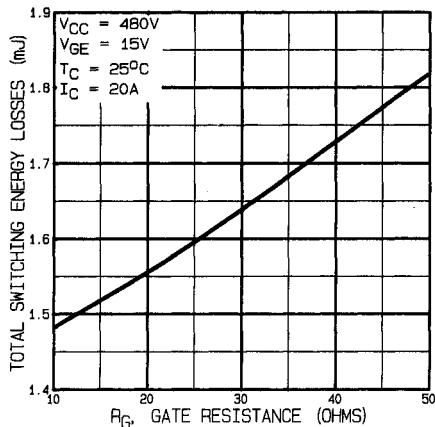


Fig. 9 — Typical Switching Losses vs. Gate Resistance

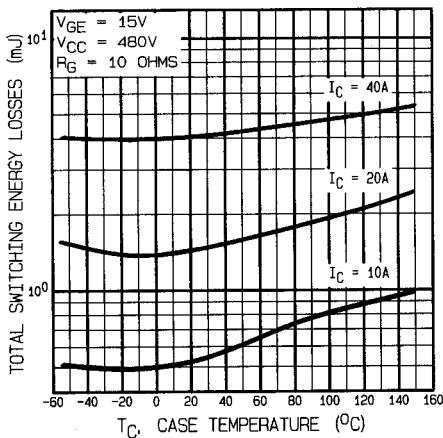


Fig. 10 — Typical Switching Losses vs. Case Temperature

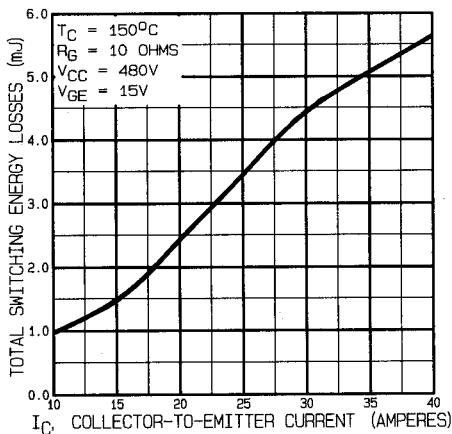


Fig. 11 — Typical Switching Losses vs. Collector-to-Emitter Current

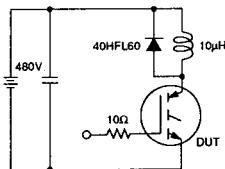


Fig 12a. Clamped Inductive Load Test Circuit

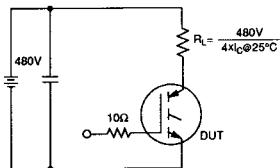


Fig 12b. Pulsed Collector Current Test Circuit

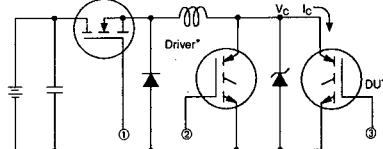


Fig 13a. Switching Loss Test Circuit

* Driver same type as DUT. $V_C = 480V$

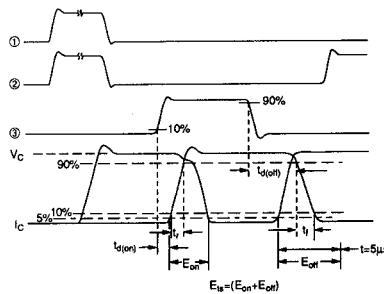


Fig 13b. Switching Loss Waveforms

For both, power dissipation = 29W

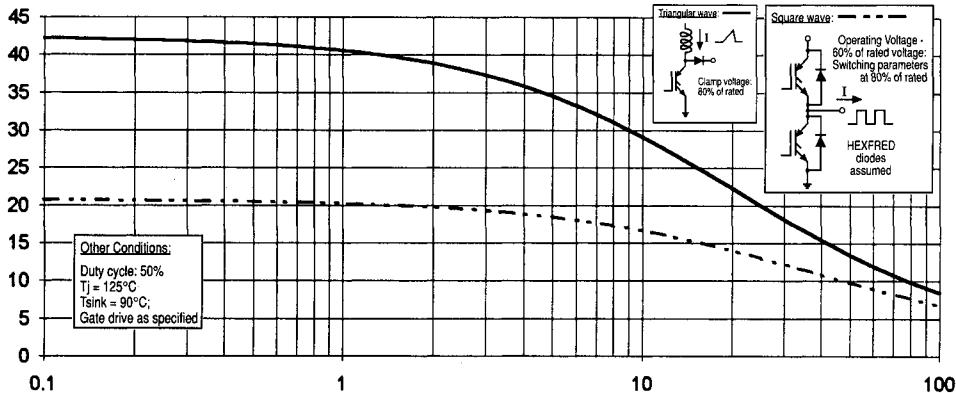
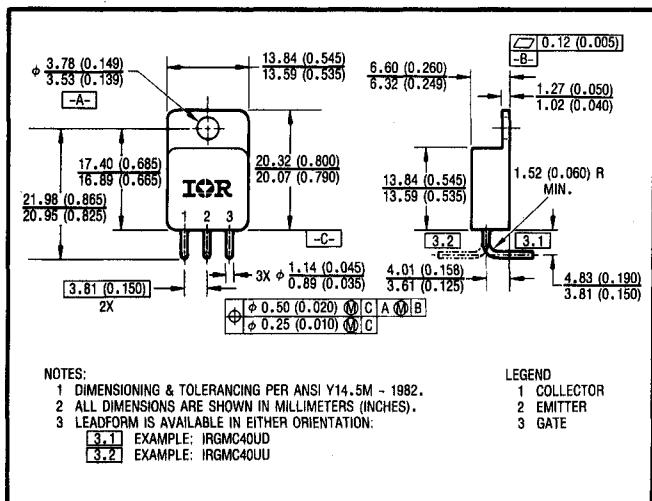


Fig. 14 — Typical Load Current vs. Frequency
(For square wave, $I = I_{\text{RMS}}$ of fundamental; for triangular wave, $I = I_{\text{PK}}$)



BERYLIA WARNING PER MIL-S-19500
Packages containing beryllia shall not be ground, sandblasted, machined, or have other operations performed on them which will produce beryllia or beryllium dust. Furthermore, beryllium oxide packages shall not be placed in acids that will produce fumes containing beryllium.

Fig. 15 – Optional Leadforms for Outline TO-254